

Electronic Patent Application Fee Transmittal

Application Number:	10814049			
Filing Date:	31-Mar-2004			
Title of Invention:	Wafer grinding using an adhesive gel material			
First Named Inventor:	Yew Wee Cheong			
Filer:	Angela Moore Sagalewicz/Heather Adamson			
Attorney Docket Number:	111079-136357			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790